

07/26/01



11000 U.S. PTO

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Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: **LUONA GOH, SIMON CHOOI, SIEW LOK TOH, TONG EARN TAY**

For: **A METHOD TO IMPROVE ADHESION OF DIELECTRIC FILMS IN DAMASCENE INTERCONNECTS**

Enclosed are:

- ☒ 5 sheets of drawing(s) - formal.
- ☒ An assignment of the invention to **Chartered Semiconductor Manufacturing Ltd.**
- ☐ An associate power of attorney ☐ Applicant claims small entity status
- Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 710.
TOTAL CLAIMS	22 -20=	2	x 18 =	\$ 36.
INDEP CLAIMS	4 -3=	1	x 80 =	\$ 80.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
			SUB TOTAL	\$ 826.
			ASSIGNMENT	\$40.
			TOTAL	\$ 866.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 866. A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 CFR \$1.16.
- ☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,

STEPHEN B. ACKERMAN, REG. NO. 37,761